



## Material Content Data Sheet



<b>Sales Product Name</b>		BSC093N04LS G		<b>Issued</b>		22. January 2018		
<b>MA#</b>		MA001506016						
<b>Package</b>		PG-TDSON-8-40		<b>Weight*</b>		118.42 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.804	0.68	0.68	6789	6789
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		319	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	copper	7440-50-8	37.762	31.88	31.92	318888	319303
wire	non noble metal	copper	7440-50-8	0.061	0.05	0.05	514	514
encapsulation	organic material	carbon black	1333-86-4	0.087	0.07		732	
	plastics	epoxy resin	-	6.851	5.79		57852	
	inorganic material	silicondioxide	60676-86-0	36.421	30.76	36.62	307567	366151
leadfinish	non noble metal	tin	7440-31-5	1.452	1.23	1.23	12259	12259
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1398	1398
solder	noble metal	silver	7440-22-4	0.028	0.02		234	
	non noble metal	tin	7440-31-5	0.022	0.02		187	
	non noble metal	lead	7439-92-1	1.060	0.90	0.94	8953	9374
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		96	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
	non noble metal	copper	7440-50-8	11.320	9.56	9.57	95595	95720
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		57	
	non noble metal	iron	7439-89-6	0.022	0.02		188	
	non noble metal	copper	7440-50-8	22.292	18.82	18.85	188247	188492
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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